

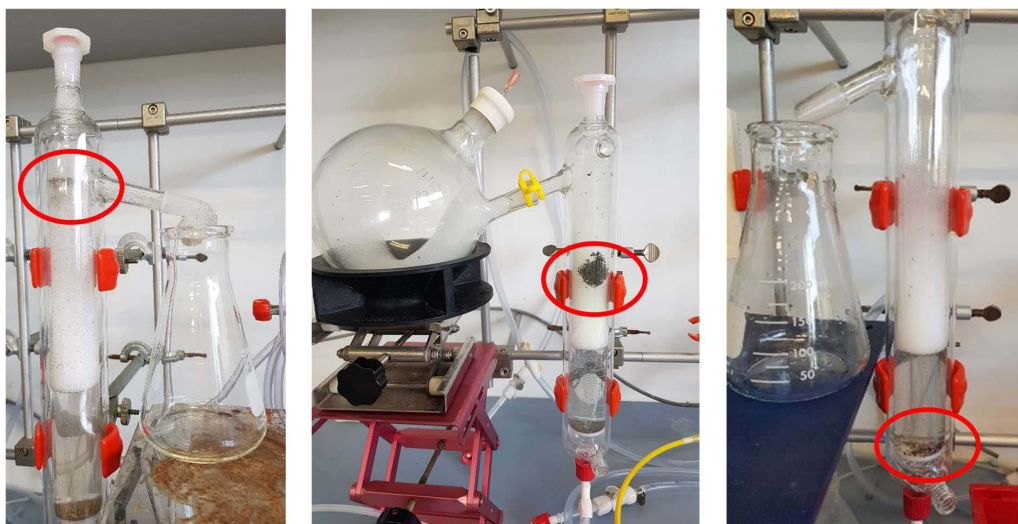
Copper leaching with aqueous foams for the processing of electronic waste

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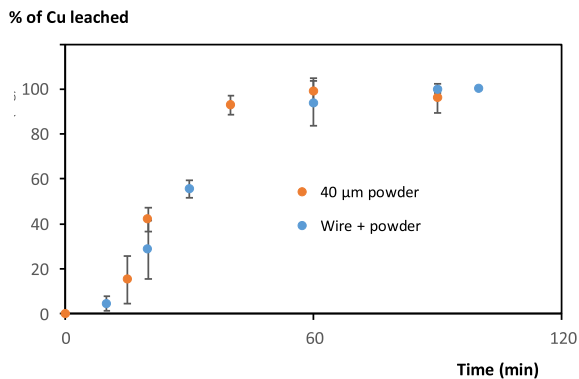
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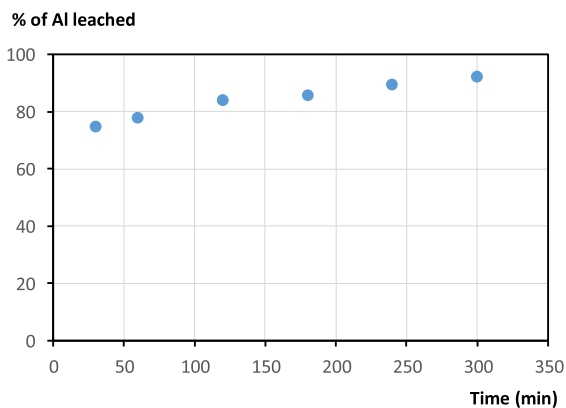


Supplementary Figure S11. Tentative set-up of leaching using foams in columns.

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Supplementary Figure SI2. Evolution of Cu leaching using foams according to the Cu source (foam prepared using 3 M HCl and 2 mM Brij S10).



Supplementary Figure SI3. Al leaching kinetics upon dissolution of WPCB (5 g of ground WPCB, size <750 μm, for 60 mL aqueous HCl solution).

Supplementary Table SI1. Leaching yield of Fe upon treatment of ground WPCB with aqueous HCl in various conditions (5 g of ground WPCB, size <750 μm, for 60 mL aqueous HCl solution)

Conditions	HCl concentration (mol·L ⁻¹)	
	3	5
5 h, rt	24%	22%
24 h, rt	25%	26%
5 h, 50 °C	24%	95%